

The Venue

We would like to invite you to Rzeszów, the capital city of Subcarpathian Voivodship, the southeastern region of Poland, adjoining the territories of Ukraine and Slovakia. For centuries Rzeszów took advantage of its location on a major east-west route linking Krakow, Przemyśl and Lviv with the Black Sea. The first recorded reference to Rzeszow dates from 1354, when it was granted a town charter by King Casimir the Great. In the 16th century the Wislok River up to Rzeszow was recognised as being navigable, giving the town a direct connection to the city of Gdańsk and that of the Baltic Sea. The period of greatest prosperity was at the end of the 16th and the beginning of the 17th centuries, when it became an important centre of trade and craftsmanship. With its population of over 172,000, Rzeszów is now one of the largest cities of the region and constitutes the economic, academic, cultural and recreational centre of south-eastern Poland. It serves as an important centre for aerospace, IT, chemical, commercial, construction and service industries. The city is also the main academic centre of the province, and well known for its polytechnic. Its historical centre is reminiscent of a village in Galicia and old town is worth a visit. The oldest monument is the 15th Century Parish Church of St. Stanislaus and Wojciech, with a Gothic chancel and three Renaissance headstones belonging to old Rzeszów families, the former owners of the town. One of the greatest attractions of Rzeszów is unique complex of underground cellars and corridors - Underground Tourist Route.

For more information see:

https://www.staypoland.com/about_rzeszow.htm/



Travel Arrangement

Air: Jasionka International Airport (IATA: RZE) is about 8 km from the city centre. Airlines: LOT Polish Airlines, Lufthansa, RyanAir.

Rail: Rzeszów is directly connected to all major cities in Poland. See <http://www.pkp.pl> for most up-to-date schedule.

Road: Rzeszów is situated on the European E-40 highway from Dresden, via Krakow to Kiev in the Ukraine, the highway E-371 from Gdansk through Warsaw to Slovakia, and A4 motorway from the Polish-German border to Polish-Ukrainian border. Road distance from Ukrainian and Slovakian border equals only around 90 km.

Accommodation

The conference will be held in a hotel located in the city centre. The accommodation will be offered for the Conference participants at the conference site.

Deadlines

Intended authors should note the following deadlines:

Receipt of papers	February 28th, 2019
Notification of acceptance of papers	April 30th, 2019
Final paper versions and 1-page abstracts	May 15th, 2019

Price Information

Standard registration fee	360 Euro
IEEE Members registration fee	300 Euro
Student registration fee	260 Euro
Late registration fee (paid after May 15 th , 2019)	450 Euro
Accompanying person social events fee	150 Euro

Conference fee includes: participation in all sessions, MIXDES 2019 Proceedings CD and other conference materials, coffee and tea during the breaks, all lunches, the Welcome Party and Conference Banquet, tourist activities (student fee does not include welcome party and closing ceremony).

Conference fee does not include accommodation and transport.



Enquiries

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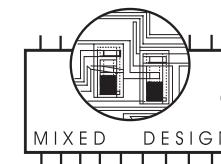
e-mail: mixdes2019@dmcs.p.lodz.pl

WWW

Information on MIXDES 2019 will be available on the World Wide Web at the following location:

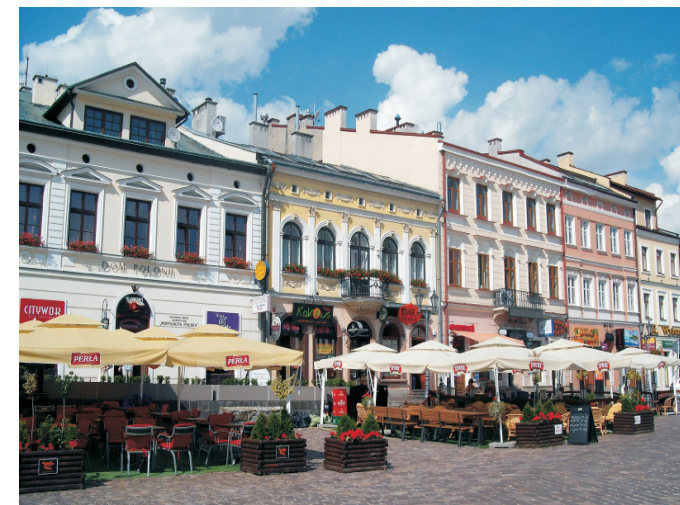
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CALL FOR PAPERS



MIXDES 2019

26th International Conference MIXED DESIGN OF INTEGRATED CIRCUITS AND SYSTEMS



An invitation to submit paper proposals and attend the Conference



Rzeszów, POLAND, 27 - 29 June 2019



MIXDES 2019

26th International Conference

MIXED DESIGN OF INTEGRATED CIRCUITS AND SYSTEMS

Rzeszów, POLAND, 27-29 June 2019

Organized by:

Department of Microelectronics and Computer Science,
Technical University of Lodz, Poland

Institute of Micro- and Optoelectronics
Warsaw University of Technology, Poland

In cooperation with:

Poland Section IEEE - CAS & ED Chapters

Section of Microelectronics and Electron Technology
of the Committee of Electronics and Telecommunication
of the Polish Academy of Sciences

Commission of Electronics and Photonics
of Polish National Committee
of International Union of Radio Science - URSI

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The MIXDES Conference

The MIXDES conference series started in Dębe near Warsaw in 1994 and has been organised yearly in the most interesting Polish cities. In 2019 we would like to continue the tradition of inviting you to the most attractive places in Poland and the conference will take place in Rzeszów, the capital of the Subcarpathian region.

In short period of time the conference has become an important event in the Central Europe allowing to discuss the recent research progress in the field of design, modelling, simulation, testing and manufacturing in various areas such as micro- and nanoelectronics, semiconductors, sensors, actuators and power devices as well as their interdisciplinary applications.

Areas of Interest

The topics of the Conference include:

- 1. Design of Integrated Circuits and Microsystems**
Design methodologies. Digital and analog synthesis. Hardware-software codesign. Reconfigurable hardware. Hardware description languages. Intellectual property-based design. Design reuse.
- 2. Thermal Issues in Microelectronics**
Thermal and electro-thermal modelling, simulation methods and tools. Thermal mapping. Thermal protection circuits.
- 3. Analysis and Modelling of ICs and Microsystems**
Simulation methods and algorithms. Behavioural modelling with VHDL-AMS and other advanced modelling languages. Microsystems modelling. Model reduction. Parameter identification.
- 4. Microelectronics Technology and Packaging**
New microelectronic technologies. Packaging. Sensors and actuators.
- 5. Testing and Reliability**
Design for testability and manufacturability. Measurement instruments and techniques.
- 6. Power Electronics**
Design, manufacturing, and simulation of power semiconductor devices. Hybrid and monolithic Smart Power circuits. Power integration.
- 7. Signal Processing**
Digital and analogue filters, telecommunication circuits. Neural networks. Artificial intelligence. Fuzzy logic. Low voltage and low power solutions.
- 8. Embedded Systems**
Design, verification and applications.
- 9. Medical Applications**
Medical and biotechnology applications. Biometrics. Thermography in medicine.

Official Language

Official language of the Conference is English, neither translation nor interpretation will be provided.

Call for Papers and Contributions

A call is made for papers, contributions and other conference activities on the topics mentioned above.

Full papers should be submitted till February 28th, 2019 - only in electronic form (MS Word, RTF, Open Office Writer, LaTeX, together with a generated PDF file).

The paper submission form and required format is available on our Web page. Authors are asked to indicate the topic into which their papers fall. The papers will be reviewed by at least two referees from the International Programme Committee. The papers will be published in the proceedings from the author's electronic submission.

Tutorials and Special Sessions - Call for Proposals

Several tutorials/special sessions will be held prior to the conference. Authors willing to propose a tutorial at MIXDES 2019 are invited to send a proposal to the Organizing Committee. The proposal should consist of a three-page summary including tutorial title, name and affiliation of the lecturer(s), tutorial objectives and audience, topical outline and provisional schedule of the tutorial.